



STN4NF20L

N-channel 200 V, 1.1 Ω , 1 A SOT-223
low gate charge STripFET™ II Power MOSFET

Preliminary data

Features

Type	V _{DSS}	R _{DS(on) max}	I _D
STN4NF20L	200 V	< 1.5 Ω	1 A

- 100% avalanche tested
- Low gate charge
- Exceptional dv/dt capability

Application

- Switching applications

Description

This Power MOSFET series realized with STMicroelectronics unique STripFET™ process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high efficiency isolated DC-DC converters.

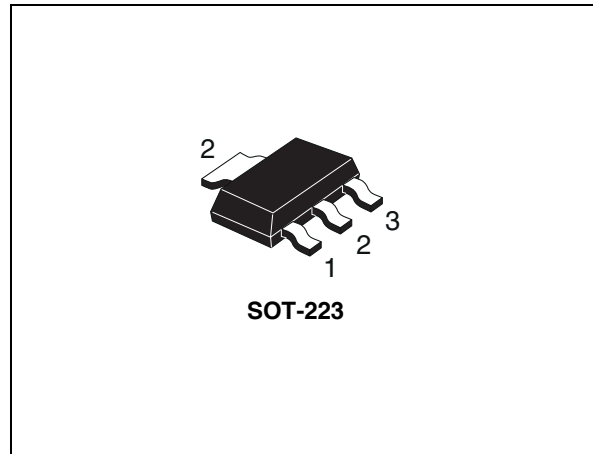


Figure 1. Internal schematic diagram

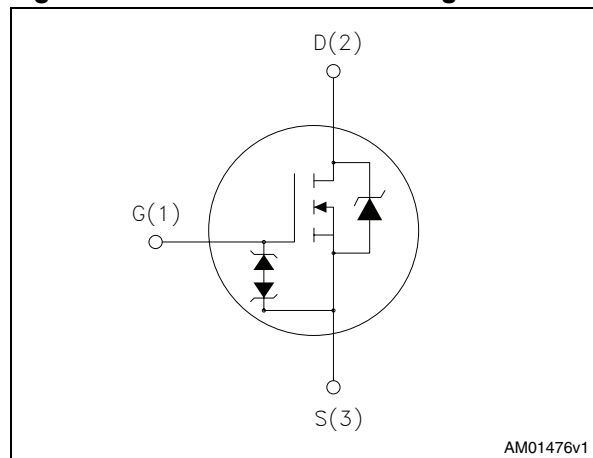


Table 1. Device summary

Order code	Marking	Package	Packaging
STN4NF20L	4NF20L	SOT-223	Tape and reel

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 20	V
I_D	Drain current continuous $T_C = 25\text{ }^\circ\text{C}$	1	A
I_D	Drain current continuous $T_C = 100\text{ }^\circ\text{C}$	0.6	A
$I_{DM}^{(1)}$	Drain current pulsed	4	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	TBD	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	TBD	V/ns
T_j T_{stg}	Operating junction temperature Storage temperature	- 55 to 150	$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2. $I_{sd} \leq \text{TBD A}$, $di/dt \leq \text{TBD A}/\mu\text{s}$, $V_{DD} \leq 80\% V_{(BR)DSS}$.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction to case	62.50	$^\circ\text{C}/\text{W}$

Table 4. Thermal data

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive ⁽¹⁾	TBD	A
E_{AS}	Single pulse avalanche energy ⁽²⁾	TBD	mJ

1. Pulse width limited by T_{JMAX} .
2. Starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$.

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 5. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0	200			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = Max rating V _{DS} = Max rating, T _C =125 °C			1 50	μA μA
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 20 V, V _{DS} =0			±100	nA
V _{GS(th)}	Gate threshold voltage	V _{GS} = V _{DS} , I _D = 250 μA	1	2	3	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 0.5 A		1.1	1.5	Ω
		V _{GS} = 5 V, I _D = 0.5 A		1.13	1.55	

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25 V, f = 1 MHz, V _{GS} = 0	-	150 30 4	-	pF pF pF
C _{oss(tr)} ⁽¹⁾	Equivalent output capacitance energy related	V _{DS} =0 to 160 V V _{GS} =0	-	TBD	-	pF
C _{oss(er)} ⁽²⁾	Equivalent output capacitance time related	V _{DS} =0 to 160 V V _{GS} =0	-	TBD	-	pF
R _g	Intrinsic gate resistance	f=1 MHz open drain	-	TBD	-	Ω
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	V _{DD} = 160 V, I _D = 1 A, V _{GS} = 10 V (see Figure 3)	-	3 TBD TBD	-	nC nC nC

1. Is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}
2. Is defined as a constant equivalent capacitance giving the same storage energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(v)}$	Voltage delay time	$V_{DD} = 100\text{ V}$, $I_D = \text{TBD}$, $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ (see Figure 2)	-	TBD	-	ns
t_r	Voltage rise time			TBD		ns
t_f	Current fall time			TBD		ns
$t_{c(off)}$	Crossing time			TBD		ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		1	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				4	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 1\text{ A}$, $V_{GS} = 0$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 1\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 20\text{ V}$ (see Figure 4)	-	TBD		ns
Q_{rr}	Reverse recovery charge			TBD		nC
I_{RRM}	Reverse recovery current			TBD		A
t_{rr}	Reverse recovery time	$I_{SD} = 1\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 20\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 4)	-	TBD		ns
Q_{rr}	Reverse recovery charge			TBD		nC
I_{RRM}	Reverse recovery current			TBD		A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

3 Test circuits

Figure 2. Switching times test circuit for resistive load

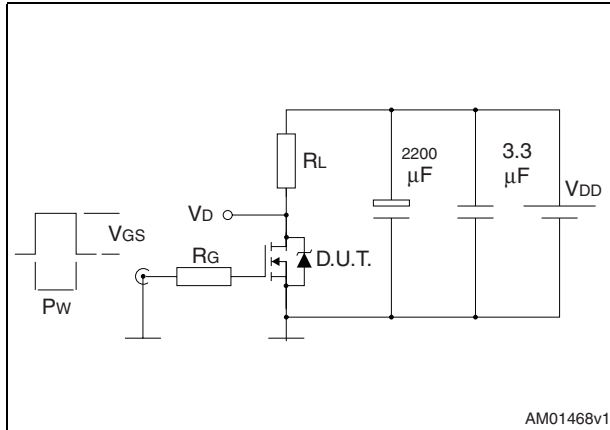


Figure 3. Gate charge test circuit

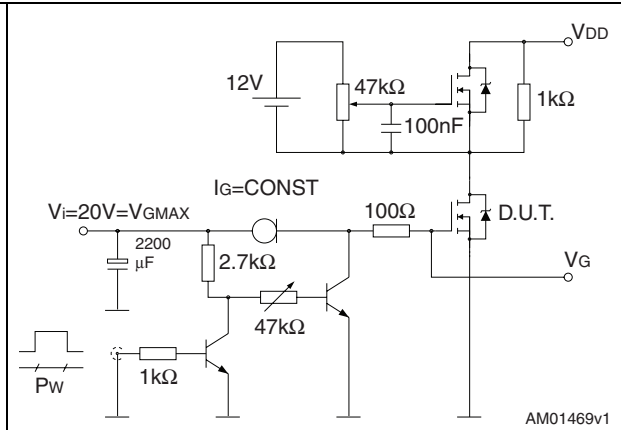


Figure 4. Test circuit for inductive load switching and diode recovery times

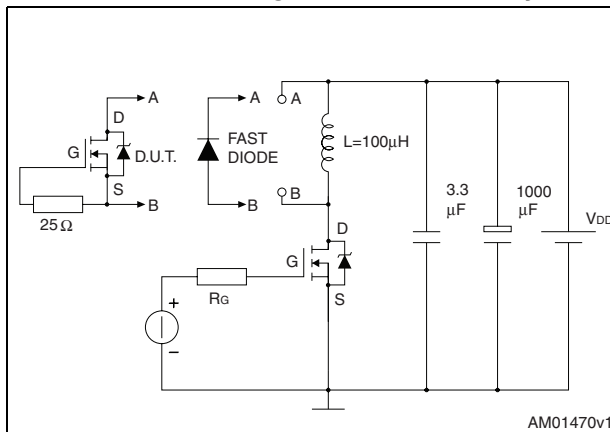


Figure 5. Unclamped inductive load test circuit

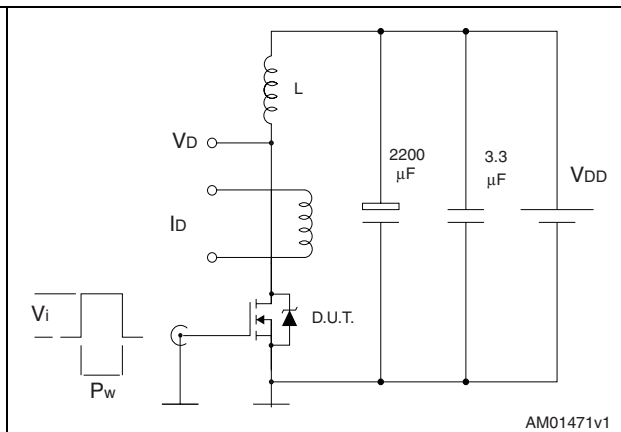


Figure 6. Unclamped inductive waveform

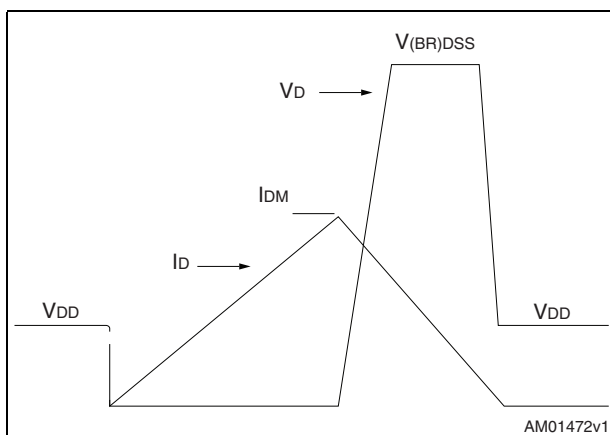
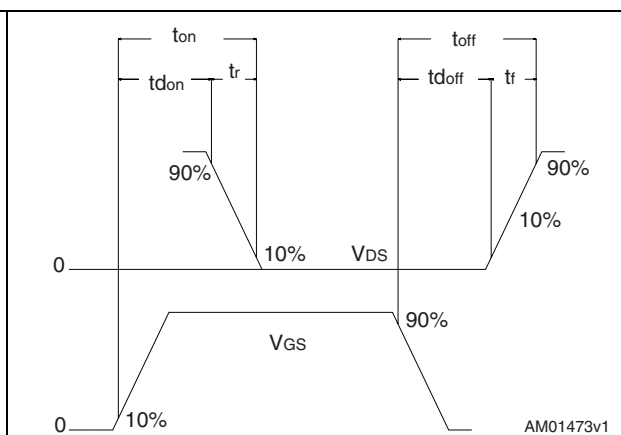


Figure 7. Switching time waveform

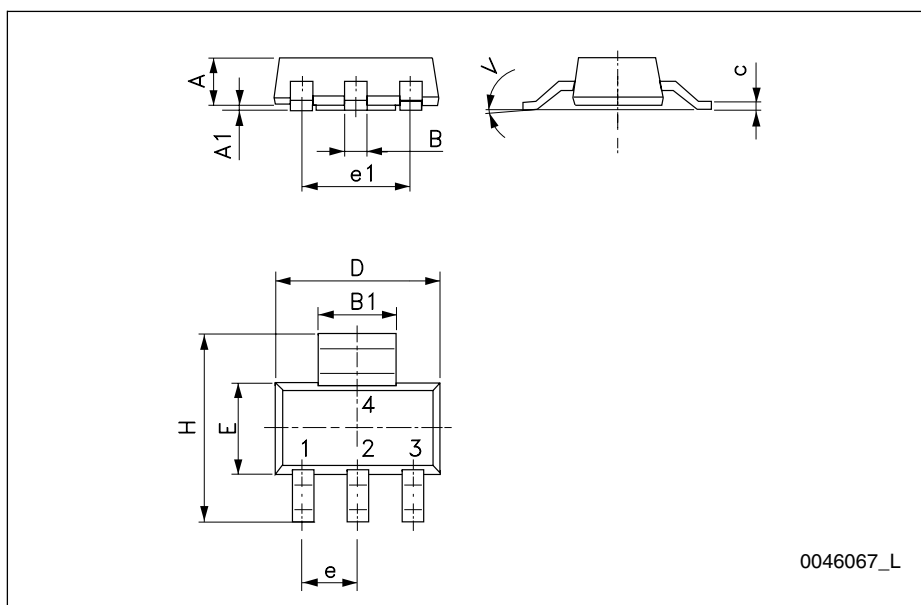


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

SOT-223 mechanical data

DIM.	mm.		
	min.	typ	max.
A			1.80
A1	0.02		0.1
B	0.60	0.70	0.85
B1	2.90	3.00	3.15
c	0.24	0.26	0.35
D	6.30	6.50	6.70
e		2.30	
e1		4.60	
E	3.30	3.50	3.70
H	6.70	7.00	7.30
V			10°



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
29-Apr-2010	1	First release.

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